



Appl. No. 09/784,234

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application Serial No. .... 09/784,234  
Filing Date ..... February 14, 2001  
Inventor..... Shozo Nagano et al.  
Assignee..... Honeywell International Inc.  
Group Art Unit..... 1742  
Examiner ..... Ip, Sikyin  
Attorney's Docket No. .... 30-5000-DIV1  
Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating Anodes,  
Metal Alloys For Use As A Conductive Interconnection In An Integrated Circuit, and  
Physical Vapor Deposition Targets

**RESPONSE TO NOVEMBER 18, 2003 FINAL ACTION AND FEBRUARY 5, 2004  
ADVISORY ACTION ACCOMPANYING FILING OF AN RCE**

To: Mail Stop RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

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**AMENDMENTS**

**Introductory Comments**

In reply to the Final Office Action dated November 18, 2003, and the subsequent  
Advisory Action, applicant amends and remarks as follows.